

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims**

1. (Currently amended) ~~A device for checking and rotating electronic components, in particular flip chips, with a pivoting part attached to a pivotal point for rotating the electronic components, on the exterior of which pivoting part a first pickup element is fixed for taking up a single electronic component from a substrate and keeping hold of it during a rotational movement of the pivoting part, characterized in that a second pickup element is arranged externally on the part opposite the first pickup element in relation to the pivotal point in such a way that in each case one pickup element is facing the substrate for each rotation of the part through 180°, and that in the pivoting part a through opening is arranged between the pickup elements in such a way that the through opening is facing the substrate for a rotation of the pivoting part through 90° or 270°.~~

A device for picking up, rotating and optically inspecting electronic components, wherein the electronic components are located on a substrate and picked up from that substrate, comprising:

an optical inspection device located generally away from and directed towards an inspection area for inspection of the surface and/or the position of at least one electronic component arranged on the substrate when the electronic component is located in the inspection area before being picked up from the substrate;

a rotationally pivoting part with an axis of rotation substantially parallel to the surface of the substrate;

two pickup elements fixed to points on the pivoting part extended from the axis of rotation of the pivoting part, each for pickup of an electronic component located at the inspection area from the substrate and for holding the electronic component during a rotational movement of the pivoting part, where the two pickup elements are substantially 180 degrees from each other with respect to the axis of rotation of the pivoting part and face opposite each other; and

wherein said pivoting part has a through opening arranged between the pickup elements such that an unobstructed optical path from the optical inspection device to the inspection area on the substrate is presented during the rotation of the pivoting part for some portion of a rotation of 180 degrees.

2. (Previously presented) Device according to Claim 1, characterized in that the first pickup element is attached on a first projection and the second pickup element on a second projection of the part.
3. (Previously presented) Device according to Claim 2, characterized in that the through opening is developed between the projections as a through channel open on one long side.

4 - 5 (Canceled)

6. (Previously presented) Device according to claim 1, characterized by a second optical facility for checking a correct position of the rotated and deposited electronic component.
7. (Withdrawn) Method for checking and rotating electronic components, in particular flip chips, which are picked up individually from a sandwich of electronic components arranged on a substrate, by means of a first pickup element arranged on a pivoting part, and are deposited in a rotated position, the pivoting part being placeable between the substrate and a first optical facility for checking the surface and the correct position of a single component arranged on the substrate, characterized in that during a 180° rotation of the pivoting part a pickup by the first pickup element of a single electronic component arranged on the substrate, a check of a surface and the correct position of a further electronic component arranged on the substrate, by means of the optical facility and a through opening arranged in the pivoting part, a depositing of the electronic component held by the first pickup element on a placing facility after a 180° rotation of the pivoting part and at the same time a further pickup of the further individual electronic component arranged on the substrate, by a second pickup element arranged externally opposite the first pickup element on the pivoting part, are executed.
8. (Withdrawn) Method according to Claim 7, characterized in that after the 180° rotation a 180° rotation in the opposite direction is executed.

9. (Withdrawn) Method according to Claim 7, characterized in that by means of a second optical facility, a correct position of the turned and deposited component is checked and adjusted during or after its transport.
10. (Withdrawn) Method according to claim 7, characterized in that the first optical facility is activated with a predefinable time delay after a rotation of the through opening into an optical connection line between the first optical facility and the electronic component still arranged on the substrate.
11. (New) A device for picking up and rotating electronic components, wherein the electronic components are located on a substrate and picked up from that substrate, for optically inspecting the electronic components with an optical inspection device located generally away from and directed towards an inspection area for inspection of the surface and/or the position of at least one electronic component arranged on the substrate when the electronic component is located in the inspection area before being picked up from the substrate, comprising:  
  
a rotationally pivoting part with an axis of rotation substantially parallel to the surface of the substrate;  
  
two pickup elements fixed to points on the pivoting part extended from the axis of rotation of the pivoting part, each for pickup of an electronic component located at the

inspection area from the substrate and for holding the electronic component during a rotational movement of the pivoting part, where the two pickup elements are substantially 180 degrees from each other with respect to the axis of rotation of the pivoting part and face opposite each other; and

wherein said pivoting part has a through opening arranged between the pickup elements such that an unobstructed optical path from the optical inspection device to the inspection area on the substrate is presented during the rotation of the pivoting part for some portion of a rotation of 180 degrees.

12. (New) Device according to Claim 11, characterized in that the first pickup element is attached on a first projection and the second pickup element on a second projection of the part.
13. (New) Device according to Claim 12, characterized in that the through opening is developed between the projections as a through channel open on one long side.
14. (New) Device according to claim 11, characterized by a second optical facility for checking a correct position of the rotated and deposited electronic component.